

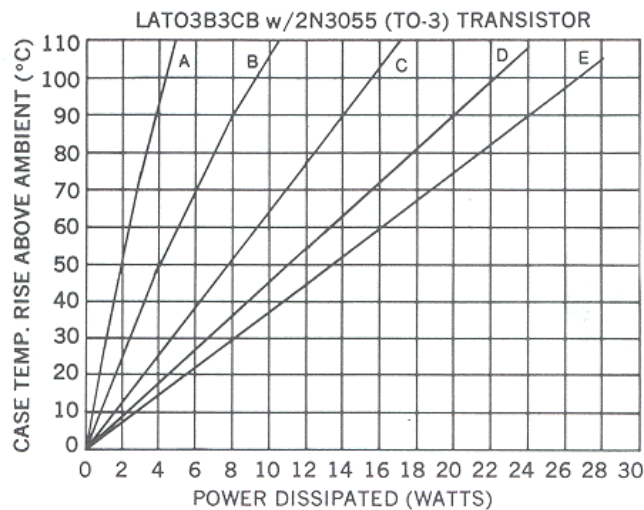
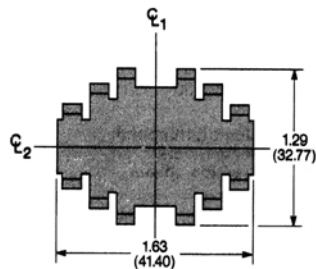
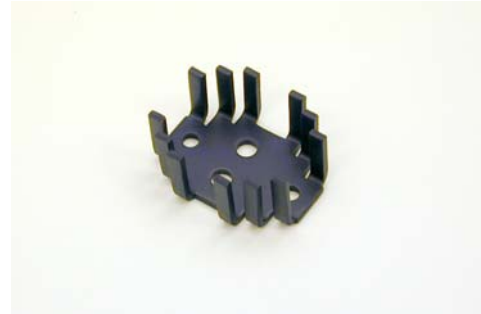
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-B3

Natural Conv. ($^{\circ}\text{C}/\text{W}$): 12

Forced Air ($^{\circ}\text{C}/\text{W}$): 3.7

Mounting Envelope: 1.63" x 1.29" x .75"



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

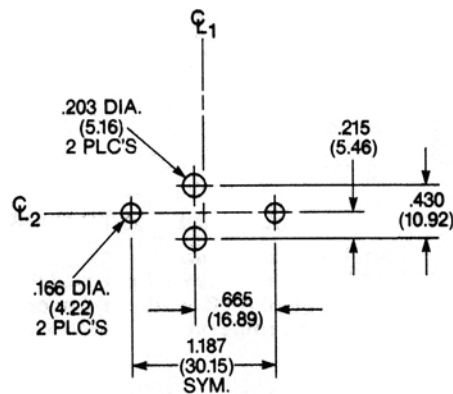
- Thermal Resistance Case to Sink is 0.1-0.3 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.7 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.

Ordering Information

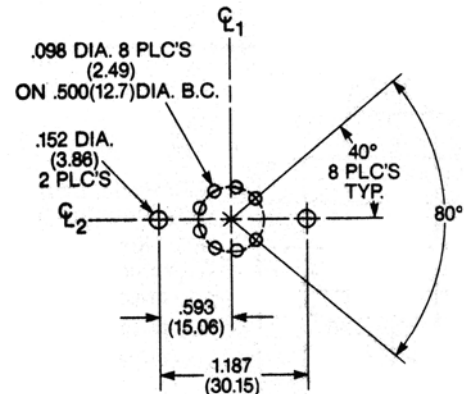
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LA000B3U	LA000B3CB	LA000B3B	Undrilled	--	10.8
LAT03B3U	LAT03B3CB	LAT03B3B	TO-3	2	10.8
LAIC3B3U	LAIC3B3CB	LAIC3B3B	TO-3 IC	4	10.8
LA407B3U	LA407B3CB	LA407B3B	TO-3 (4-pin)	5	10.8
LA394B3U	LA394B3CB	LA394B3B	Universal	8	10.8

HOLE PATTERNS

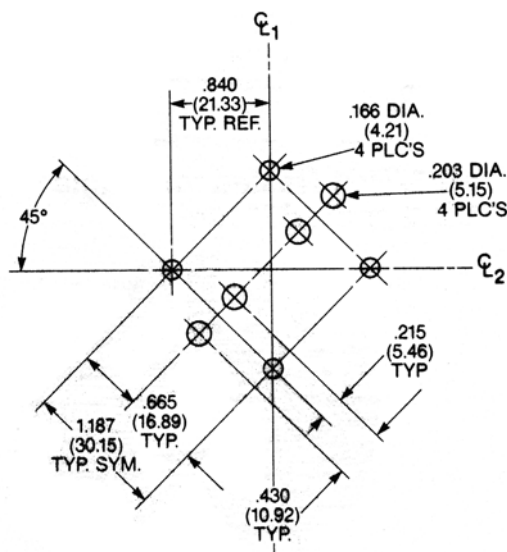
2. Hole Pattern no. 236 accommodates TO-3s. Available in LA-B series heat dissipators only.



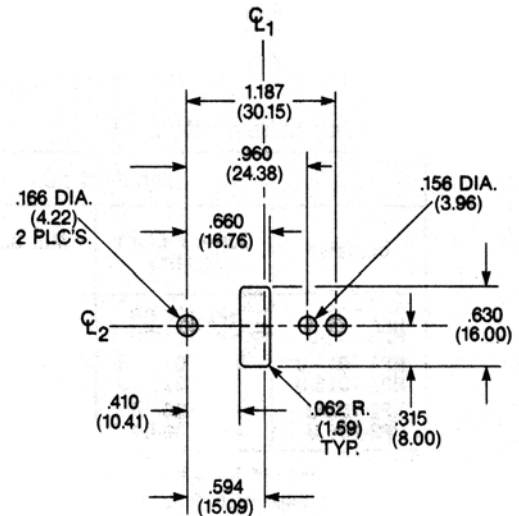
4. Hole pattern no. 237 accommodates To-3 ICs. Available in LA-B series heat dissipators only.



5. Hole pattern no. 407 accommodates TO-3s (4-pin). Available in LA-B series heat dissipators only.



8. Hole pattern no. 394 (universal) accommodates TO-3s, TO-66s, TO-126s, TO-127s, or T-220s. Available in LA-B series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

413 North Moss Street, Burbank, California 91502 Tel: (818) 842-7277 Fax: (818) 848-8872

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